VSMY98545



Vishay Semiconductors

High Power Infrared Emitting Diode, 850 nm, **Surface Emitter Technology**



FEATURES

- · Package type: surface mount
- · Package form: high power SMD with lens
- Dimensions (L x W x H in mm): 3.85 x 3.85 x 2.24
- Peak wavelength: $\lambda_p = 850 \text{ nm}$
- · High reliability
- · High radiant power
- High radiant intensity
- Angle of half intensity: $\varphi = \pm 45^{\circ}$
- · Low forward voltage
- Designed for high drive currents: up to 1 A (DC) and up to 5 A pulses
- Low thermal resistance: R_{th.IP} = 10 K/W
- Floor life: 168 h, MSL 3, according to J-STD-020
- · Lead (Pb)-free reflow soldering
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Infrared illumination for CMOS cameras (CCTV)
- Illumination for cameras (3D gaming)
- Machine vision
- 3D TV

DESCRIPTION

As part of the <u>SurfLightTM</u> portfolio, the VSMY98545 is an infrared, 850 nm emitting diode based on surface emitter technology with high radiant power and high speed, molded in low thermal resistance SMD package with lens. A 42 mil chip provides outstanding low forward voltage and allows DC operation of the device up to 1 A.

PRODUCT SUMMARY				
COMPONENT	l _e (mW/sr)	φ (deg)	λ _p (nm)	t _r (ns)
VSMY98545	350	± 45	850	15

Note

Test conditions see table "Basic Characteristics"

ORDERING INFORMATION					
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM		
VSMY98545	Tape and reel	MOQ: 600 pcs, 600 pcs/reel	High power with lens		

Note

MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)					
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT	
Reverse voltage		V _R	5	V	
Forward current		I _F	1	A	
Peak forward current	$t_p/T = 0.5, t_p = 100 \ \mu s$	I _{FM}	2	A	
Surge forward current	t _p = 100 μs	I _{FSM}	5	A	
Power dissipation		Pv	2.3	W	
Junction temperature		Τj	125	°C	
Operating temperature range		T _{amb}	-40 to +95	°C	
Storage temperature range		T _{stg}	-40 to +100	°C	
Soldering temperature	Acc. figure 10, J-STD-20	T _{sd}	260	°C	
Thermal resistance junction/pin	Acc. J-STD-051, soldered on PCB	R _{thJP}	10	K/W	

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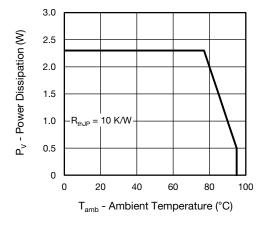


GREEN

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Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

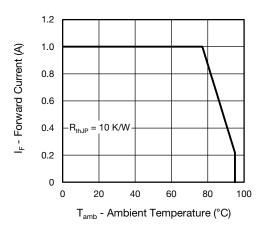


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I _F = 1 A, t _p = 20 ms	V _F		1.8	2.3	V
	I _F = 5 A, t _p = 100 μs	V _F		3.3		V
Temperature coefficient of V_F	I _F = 1 A	TK _{VF}		-0.74		mV/K
Reverse current	V _R = 5 V	I _R	not designed for reverse operation			μA
Dedient intensity	I _F = 1 A, t _p = 20 ms	I _e	230	350	550	mW/sr
Radiant intensity	I _F = 5 A, t _p = 100 μs	I _e		1600		mW/sr
Radiant power	I _F = 1 A, t _p = 20 ms	фе		660		mW
Temperature coefficient of ϕ_{e}	I _F = 1 A	TKφ _e		-0.14		%/K
Angle of half intensity		φ		± 45		deg
Peak wavelength	I _F = 1 A	λρ		850		nm
Spectral bandwidth	I _F = 1 A	Δλ		30		nm
Temperature coefficient of λ_p	I _F = 1 A	TKλ _p		0.2		nm/K
Rise time	I _F = 1 A	t _r		15		ns
Fall time	I _F = 1 A	t _f		18		ns



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BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

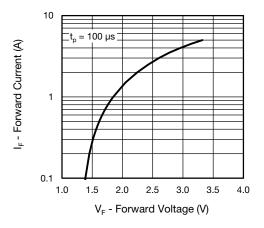


Fig. 3 - Forward Current vs. Forward Voltage

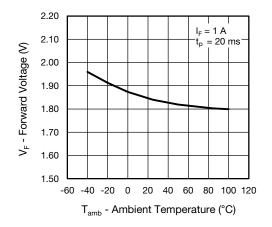


Fig. 4 - Forward Voltage vs. Ambient Temperature

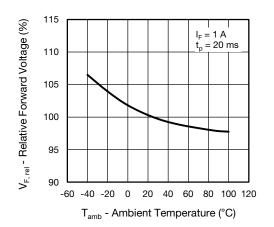


Fig. 5 - Relative Forward Voltage vs. Ambient Temperature

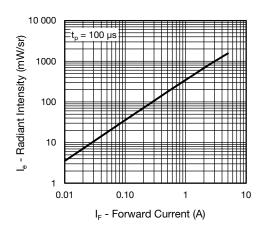


Fig. 6 - Radiant Intensity vs. Forward Current

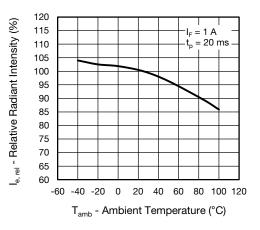


Fig. 7 - Relative Radiant Intensity vs. Ambient Temperature

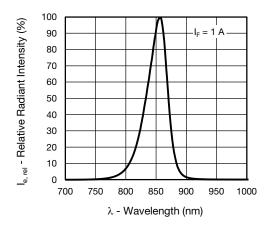


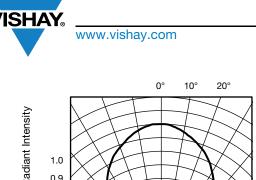
Fig. 8 - Relative Radiant Power vs. Wavelength

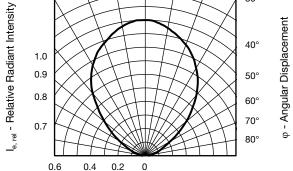
3 estions, contact: emittertechsupport@

For technical questions, contact: <u>emittertechsupport@vishay.com</u> THIS DOCUMENT IS SUBJECT TO CHANGE WITHOUT NOTICE. THE PRODUCTS DESCRIBED HEREIN AND THIS DOCUMENT ARE SUBJECT TO SPECIFIC DISCLAIMERS, SET FORTH AT <u>www.vishay.com/doc?91000</u>





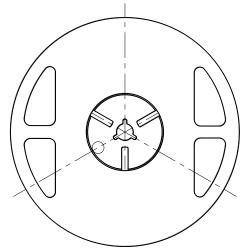


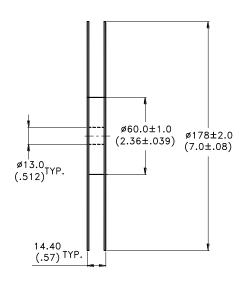


30°

Fig. 9 - Relative Radiant Intensity vs. Angular Displacement

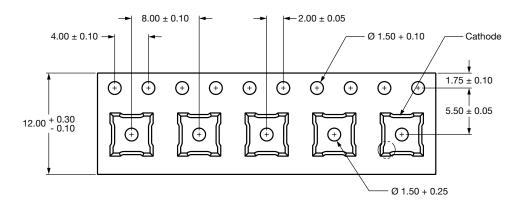
TAPING DIMENSIONS in millimeters





Notes

- Empty component pockets sealed with top cover tape.
- 7 inch reel 600 pieces per reel.
- The maximum number of consecutive missing lamps is two.
- In accordance with ANSI/EIA 481-1-A-1994 specifications.



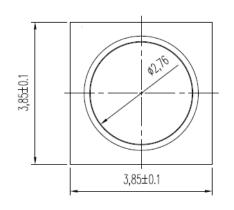
4 For technical questions, contact: <u>emittertechsupport@vishay.com</u> Document Number: 81223

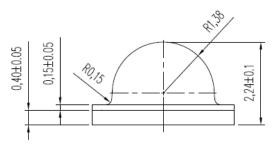
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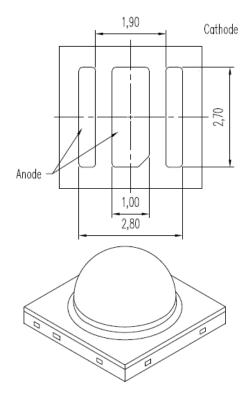




PACKAGE DIMENSIONS in millimeters

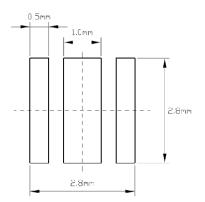






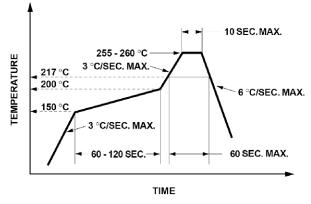
Notes

- Tolerance is \pm 0.10 mm (0.004") unless otherwise noted.
- Specifications are subject to change without notice.



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SOLDER PROFILE



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Fig. 10 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 168 h

Conditions: T_{amb} < 30 °C, RH < 60 %

Moisture sensitivity level 3, acc. to J-STD-020B

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.



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